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(12) United States Patent

Howell

(54) METHOD OF CONSTRUCTING AN INTERPOSER

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(57) **ABSTRACT**

According to one aspect of the present invention, a method of constructing an interposer is provided. A conductive layer is formed on a nonconductive layer. The conductive layer has via portions, non-via portions, and first and second opposing surfaces. The first surface of the conductive layer is adjacent to the nonconductive layer. Portions of the nonconductive layer are removed to expose portions of the first surface of the conductive layer. Conductive pads are formed on the exposed portions of the first surface and the second surface of the conductive layer. The non-via portions of the conductive layer are removed to form a plurality of electrically separated conductors. Each conductor includes at least two conductive pads and a via portion of the conductive layer.

20 Claims, 11 Drawing Sheets

